

L25	78283	(chip or die or semiconductor) and ((compliant or spring or flexible) same connect\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/12 16:18
L26	3647	25 and (cool\$3 same liquid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/12 16:20
L27	2064	26 and spring\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/12 16:20
L28	251	"361"/\$.ccls. and 27	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/12 16:20
L29	111	(361/690).CCLS.	US-PGPUB	OR	OFF	2006/01/12 16:31
L31	0	(361/693).CCLS.	US-PGPUB	OR	OFF	2006/01/12 16:32
L32	164	(361/699).CCLS.	US-PGPUB	OR	OFF	2006/01/12 16:32
L33	47	(257/714).CCLS.	US-PGPUB	OR	OFF	2006/01/12 16:34
L34	260	(62/259.2).CCLS.	US-PGPUB	OR	OFF	2006/01/12 16:35
L35	283	(165/104.33).CCLS.	US-PGPUB	OR	OFF	2006/01/12 16:35